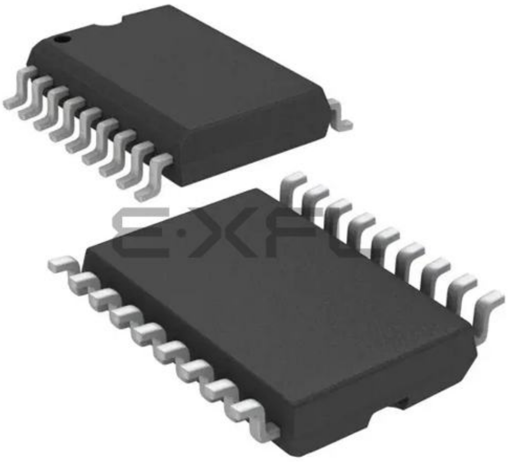

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f54t-i-so

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NOTES:

2.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3 and Q4. Internally, the Program Counter (PC) is incremented every Q1 and the instruction is fetched from program memory and latched into the instruction register in Q4. It is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 2-2 and Example 2-1.

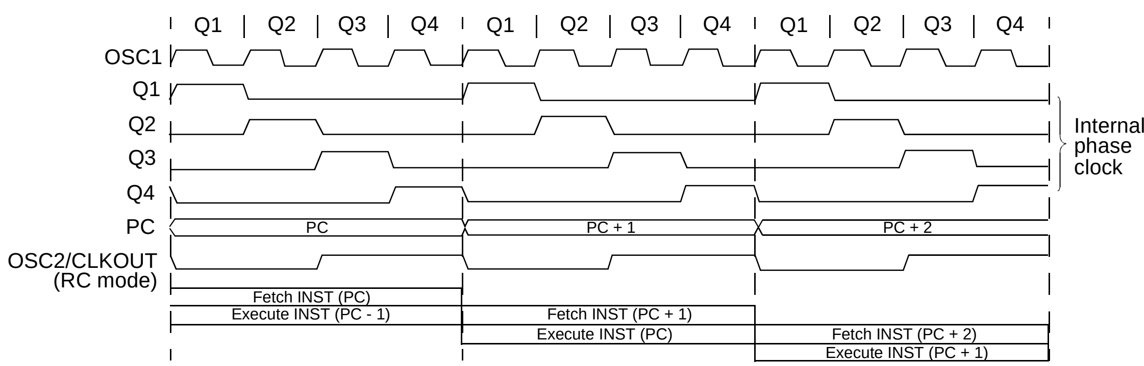
2.2 Instruction Flow/Pipelining

An instruction cycle consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle, while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the Program Counter to change (e.g., `GOTO`), then two cycles are required to complete the instruction (Example 2-1).

A fetch cycle begins with the Program Counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the instruction register in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 2-2: CLOCK/INSTRUCTION CYCLE



EXAMPLE 2-1: INSTRUCTION PIPELINE FLOW

1. `MOVLW H'55'`	Fetch 1	Execute 1				
2. `MOVWF PORTB`		Fetch 2	Execute 2			
3. `CALL SUB_1`			Fetch 3	Execute 3		
4. `BSF PORTA, BIT3`				Fetch 4	Flush	
					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline, while the new instruction is being fetched and then executed.

3.2 Data Memory Organization

Data memory is composed of registers or bytes of RAM. Therefore, data memory for a device is specified by its register file. The register file is divided into two functional groups: Special Function Registers (SFR) and General Purpose Registers (GPR).

The Special Function Registers include the TMR0 register, the Program Counter (PC), the STATUS register, the I/O registers (ports) and the File Select Register (FSR). In addition, Special Purpose Registers are used to control the I/O port configuration and prescaler options.

The General Purpose Registers are used for data and control information under command of the instructions.

For the PIC16F54, the register file is composed of 7 Special Function Registers and 25 General Purpose Registers (Figure 3-3).

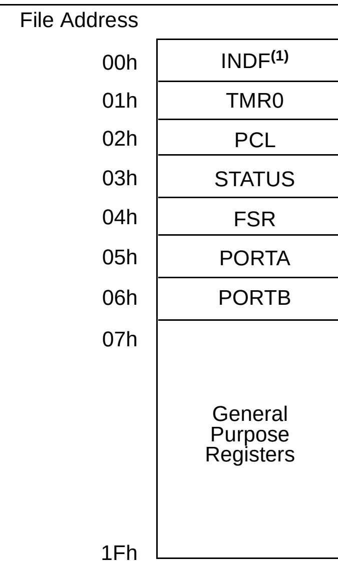
For the PIC16F57, the register file is composed of 8 Special Function Registers, 8 General Purpose Registers and 64 additional General Purpose Registers that may be addressed using a banking scheme (Figure 3-4).

For the PIC16F59, the register file is composed of 10 Special Function Registers, 6 General Purpose Registers and 128 additional General Purpose Registers that may be addressed using a banking scheme (Figure 3-5).

3.2.1 GENERAL PURPOSE REGISTER FILE

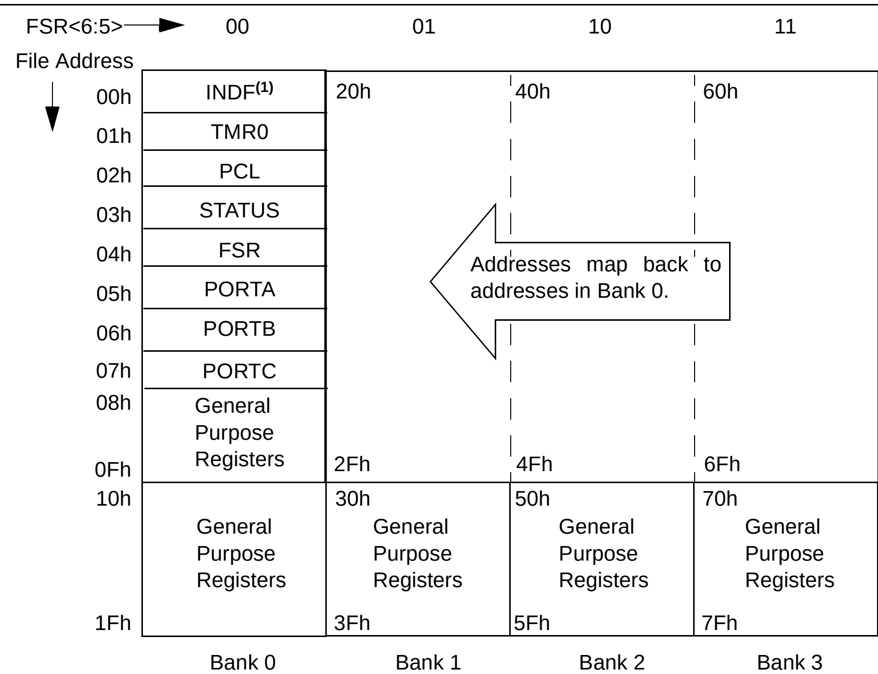
The register file is accessed either directly or indirectly through the File Select Register (FSR). The FSR register is described in **Section 3.7 “Indirect Data Addressing; INDF and FSR Registers”**.

FIGURE 3-3: PIC16F54 REGISTER FILE MAP



Note 1: Not a physical register. See **Section 3.7 “Indirect Data Addressing; INDF and FSR Registers”**.

FIGURE 3-4: PIC16F57 REGISTER FILE MAP



Note 1: Not a physical register. See **Section 3.7 “Indirect Data Addressing; INDF and FSR Registers”**.

3.5 Program Counter

As a program instruction is executed, the Program Counter (PC) will contain the address of the next program instruction to be executed. The PC value is increased by one, every instruction cycle, unless an instruction changes the PC.

For a `GOTO` instruction, bits 8:0 of the PC are provided by the `GOTO` instruction word. The PC Latch (PCL) is mapped to PC<7:0> (Figure 3-6 and Figure 3-7).

For the PIC16F57 and PIC16F59, a page number must be supplied as well. Bit 5 and bit 6 of the STATUS register provide page information to bit 9 and bit 10 of the PC (Figure 3-6 and Figure 3-7).

For a `CALL` instruction, or any instruction where the PCL is the destination, bits 7:0 of the PC again are provided by the instruction word. However, PC<8> does not come from the instruction word, but is always cleared (Figure 3-6 and Figure 3-7).

Instructions where the PCL is the destination or modify PCL instructions, include `MOVWF PCL`, `ADDWF PCL`, and `BSF PCL,5`.

For the PIC16F57 and PIC16F59, a page number again must be supplied. Bit 5 and bit 6 of the STATUS register provide page information to bit 9 and bit 10 of the PC (Figure 3-6 and Figure 3-7).

> **Note:** Because PC<8> is cleared in the `CALL` instruction or any modified PCL instruction, all subroutine calls or computed jumps are limited to the first 256 locations of any program memory page (512 words long).

FIGURE 3-6: LOADING OF PC BRANCH INSTRUCTIONS – PIC16F54

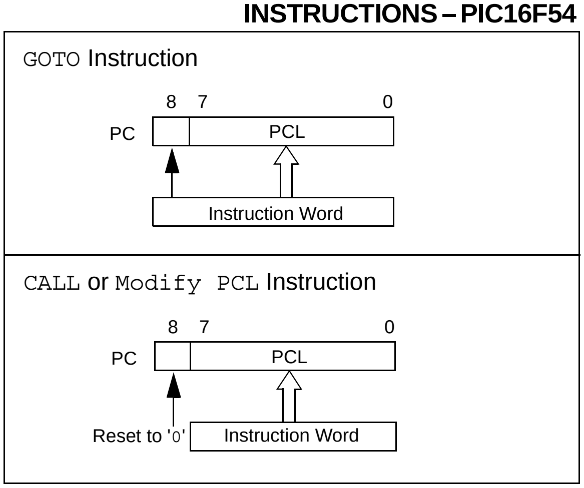
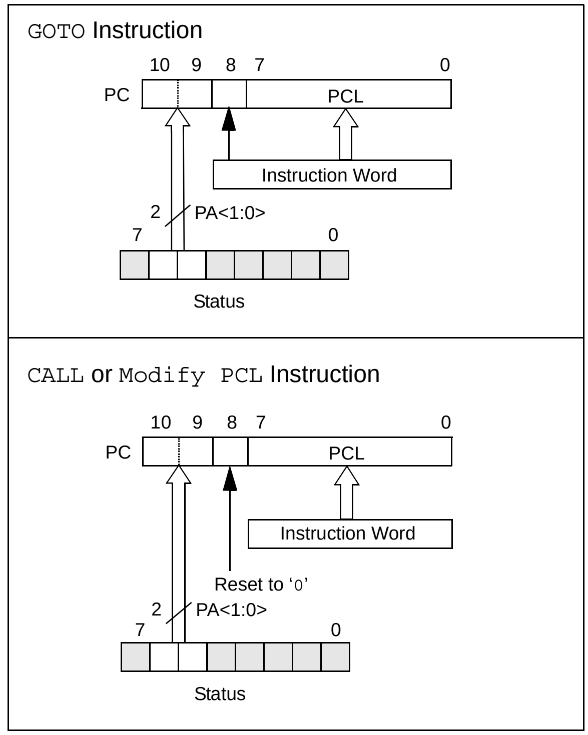


FIGURE 3-7: LOADING OF PC BRANCH INSTRUCTIONS – PIC16F57 AND PIC16F59



3.5.1 PAGING CONSIDERATIONS PIC16F57 AND PIC16F59

If the PC is pointing to the last address of a selected memory page, when it increments, it will cause the program to continue in the next higher page. However, the page preselect bits in the STATUS register will not be updated. Therefore, the next `GOTO`, `CALL` or `MODIFY PCL` instruction will send the program to the page specified by the page preselect bits (PA0 or PA<1:0>).

For example, a `NOP` at location 1FFh (page 0) increments the PC to 200h (page 1). A `GOTO xxx` at 200h will return the program to address xxh on page 0 (assuming that PA<1:0> are clear).

To prevent this, the page preselect bits must be updated under program control.

3.5.2 EFFECTS OF RESET

The PC is set upon a Reset, which means that the PC addresses the last location in the last page (i.e., the Reset vector).

The STATUS register page preselect bits are cleared upon a Reset, which means that page 0 is preselected.

Therefore, upon a Reset, a `GOTO` instruction at the Reset vector location will automatically cause the program to jump to page 0.

3.6 Stack

The PIC16F54 device has a 9-bit wide, two-level hardware PUSH/POP stack. The PIC16F57 and PIC16F59 devices have an 11-bit wide, two-level hardware PUSH/POP stack.

A `CALL` instruction will PUSH the current value of stack 1 into stack 2 and then PUSH the current program counter value, incremented by one, into stack level 1. If more than two sequential `CALL`'s are executed, only the most recent two return addresses are stored.

A `RETLW` instruction will POP the contents of stack level 1 into the program counter and then copy stack level 2 contents into level 1. If more than two sequential `RETLW`'s are executed, the stack will be filled with the address previously stored in level 2.

Note:	The W register will be loaded with the literal value specified in the instruction. This is particularly useful for the implementation of data look-up tables within the program memory.

For the `RETLW` instruction, the PC is loaded with the Top-of-Stack (TOS) contents. All of the devices covered in this data sheet have a two-level stack. The stack has the same bit width as the device PC, therefore, paging is not an issue when returning from a subroutine.

3.7 Indirect Data Addressing; INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR Register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 3-1: INDIRECT ADDRESSING

- Register file 08 contains the value 10h
- Register file 09 contains the value 0Ah
- Load the value 08 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 09h)
- A read of the INDF register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = `0`) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although Status bits may be affected).

A simple program to clear RAM locations 10h-1Fh using indirect addressing is shown in Example 3-2.

EXAMPLE 3-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

```
         MOVLW  H'10'  ;initialize pointer
         MOVWF  FSR    ;to RAM
NEXT     CLRF   INDF   ;clear INDF Register
         INCF   FSR,F  ;inc pointer
         BTFSC  FSR,4  ;all done?
         GOTO   NEXT   ;NO, clear next
CONTINUE
         :             ;YES, continue
```

The FSR is either a 5-bit (PIC16F54), 7-bit (PIC16F57) or 8-bit (PIC16F59) wide register. It is used in conjunction with the INDF register to indirectly address the data memory area.

The FSR<4:0> bits are used to select data memory addresses 00h to 1Fh.

PIC16F54: This does not use banking. FSR<7:5> bits are unimplemented and read as '`1`'s.

PIC16F57: FSR<7> bit is unimplemented and read as '`1`'. FSR<6:5> are the bank select bits and are used to select the bank to be addressed (`00` = Bank 0, `01` = Bank 1, `10` = Bank 2, `11` = Bank 3).

PIC16F59: FSR<7:5> are the bank select bits and are used to select the bank to be addressed (`000` = Bank 0, `001` = Bank 1, `010` = Bank 2, `011` = Bank 3, `100` = Bank 4, `101` = Bank 5, `110` = Bank 6, `111` = Bank 7).

Note:	A `CLRF FSR` instruction may not result in an FSR value of 00h if there are unimplemented bits present in the FSR.

4.0 OSCILLATOR CONFIGURATIONS

4.1 Oscillator Types

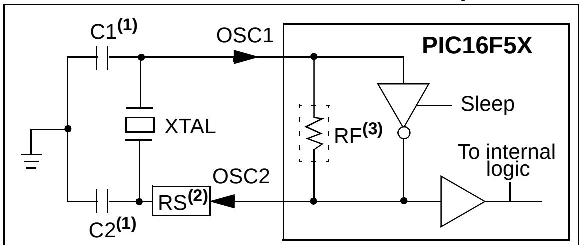
The PIC16F5X devices can be operated in four different oscillator modes. The user can program two Configuration bits (FOSC1:FOSC0) to select one of these four modes:

- LP: Low-power Crystal
- XT: Crystal/Resonator
- HS: High-speed Crystal/Resonator
- RC: Resistor/Capacitor

4.2 Crystal Oscillator/Ceramic Resonators

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 4-1). The PIC16F5X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency outside of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source drive the OSC1/CLKIN pin (Figure 4-2).

FIGURE 4-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Capacitor Selection tables for recommended values of C1 and C2.
2: A series resistor (RS) may be required.
3: RF varies with the Oscillator mode chosen (approx. value = 10 MΩ).

FIGURE 4-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

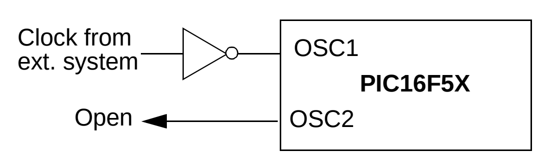


TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Osc Type	Resonator Freq.	Cap. Range C1	Cap. Range C2
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-33 pF 10-22 pF	68-100 pF 15-33 pF 10-22 pF
HS	8.0 MHz 16.0 MHz	10-22 pF 10 pF	10-22 pF 10 pF

These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq.	Cap.Range C1	Cap. Range C2
LP	32 kHz(1)	15 pF	15 pF
XT	100 kHz 200 kHz 455 kHz 1 MHz 2 MHz 4 MHz	15-30 pF 15-30 pF 15-30 pF 15-30 pF 15 pF 15 pF	200-300 pF 100-200 pF 15-100 pF 15-30 pF 15 pF 15 pF
HS	4 MHz 8 MHz 20 MHz	15 pF 15 pF 15 pF	15 pF 15 pF 15 pF

Note 1: For V_{DD} > 4.5V, C1 = C2 ≈ 30 pF is recommended.

These values are for design guidance only. Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specifications. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

Note 1: This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this device.

2: The user should verify that the device oscillator starts and performs as expected. Adjusting the loading capacitor values and/or the Oscillator mode may be required.

TABLE 6-1: SUMMARY OF PORT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on MCLR and WDT Reset
N/A	TRIS	I/O Control Registers (TRISA, TRISB, TRISC, TRISD and TRISE)								1111 1111	1111 1111
05h	PORTA	—	—	—	—	RA3	RA2	RA1	RA0	---- xxxx	---- uuuu
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h	PORTC(1)	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
08h	PORTD(2)	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	uuuu uuuu
09h	PORTE(2)	RE7	RE6	RE5	RE4	—	—	—	—	xxxx ----	uuuu ----

Legend: Shaded cells = unimplemented, read as '0', – = unimplemented, read as '0', x = unknown, u = unchanged

Note 1: File address 07h is a General Purpose Register on the PIC16F54.

2: File address 08h and 09h are General Purpose Registers on the PIC16F54 and PIC16F57.

7.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

7.1.1 EXTERNAL CLOCK SYNCHRONIZATION

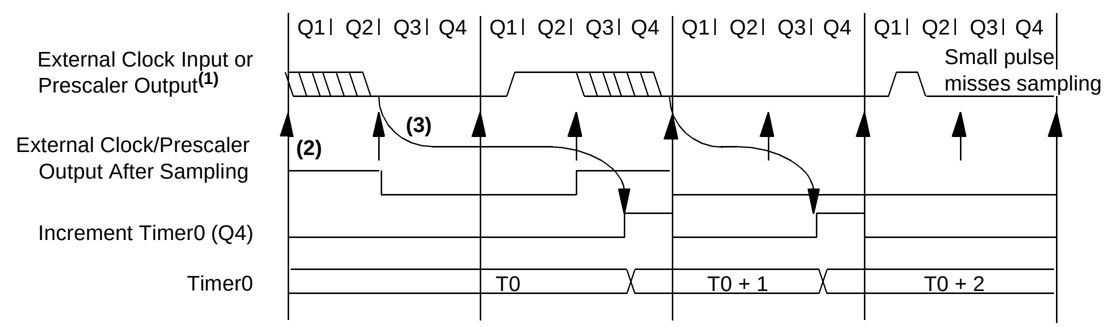
When no prescaler is used, the external clock is the Timer0 input. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 7-4). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

7.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 7-4 shows the delay from the external clock edge to the timer incrementing.

FIGURE 7-4: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: External clock if no prescaler selected; prescaler output otherwise.

2: The arrows indicate the points in time where sampling occurs.

3: Delay from clock input change to Timer0 increment is 3TOSC to 7TOSC (duration of Q = TOSC). Therefore, the error in measuring the interval between two edges on Timer0 input = ± 4TOSC max.

7.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer (WDT), respectively (**Section 8.2.1 “WDT Period”**). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the WDT, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1`, `MOVWF 1`, `BSF 1`, `x`, etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the WDT. The prescaler is neither readable nor writable. On a Reset, the prescaler contains all ‘`0`’s.

IORLW — Inclusive OR literal with W

Syntax:	[*label*] IORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .OR. (k) → (W)
Status Affected:	Z
Encoding:	`1101` `kkkk` `kkkk`
Description:	The contents of the W register are OR'ed with the eight-bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
<u>Example</u>:	`IORLW` 0x35

Before Instruction
W = 0x9A
After Instruction
W = 0xBF
Z = 0

IORWF — Inclusive OR W with f

Syntax:	[*label*] IORWF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W).OR. (f) → (dest)
Status Affected:	Z
Encoding:	`0001` `00df` `ffff`
Description:	Inclusive OR the W register with register 'f'. If 'd' is '`0`', the result is placed in the W register. If 'd' is '`1`', the result is placed back in register 'f'.
Words:	1
Cycles:	1
<u>Example</u>:	`IORWF RESULT, 0`

Before Instruction
RESULT = 0x13
W = 0x91
After Instruction
RESULT = 0x13
W = 0x93
Z = 0

MOVF — Move f

Syntax:	[*label*] MOVF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f) → (dest)
Status Affected:	Z
Encoding:	`0010` `00df` `ffff`
Description:	The contents of register 'f' is moved to destination 'd'. If 'd' is '`0`', destination is the W register. If 'd' is '`1`', the destination is file register 'f'. 'd' is '`1`' is useful to test a file register since Status flag Z is affected.
Words:	1
Cycles:	1
<u>Example</u>:	`MOVF FSR, 0`

After Instruction
W = value in FSR register

MOVLW — Move Literal to W

Syntax:	[*label*] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W)
Status Affected:	None
Encoding:	`1100` `kkkk` `kkkk`
Description:	The eight-bit literal 'k' is loaded into the W register.
Words:	1
Cycles:	1
<u>Example</u>:	`MOVLW` 0x5A

After Instruction
W = 0x5A

MOVWF — Move W to f

Syntax:	[*label*] MOVWF f
Operands:	$0 \le f \le 31$
Operation:	(W) $\rightarrow$ (f)
Status Affected:	None
Encoding:	`0000` `001f` `ffff`
Description:	Move data from the W register to register 'f'.
Words:	1
Cycles:	1
Example:	`MOVWF TEMP_REG`

Before Instruction
TEMP_REG = 0xFF
W = 0x4F
After Instruction
TEMP_REG = 0x4F
W = 0x4F

NOP — No Operation

Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Encoding:	`0000` `0000` `0000`
Description:	No operation.
Words:	1
Cycles:	1
Example:	`NOP`

OPTION — Load OPTION Register

Syntax:	[*label*] OPTION
Operands:	None
Operation:	(W) $\rightarrow$ OPTION
Status Affected:	None
Encoding:	`0000` `0000` `0010`
Description:	The content of the W register is loaded into the Option register.
Words:	1
Cycles:	1
Example:	`OPTION`

Before Instruction
W = 0x07
After Instruction
OPTION = 0x07

RETLW — Return with Literal in W

Syntax:	[*label*] RETLW k
Operands:	$0 \le k \le 255$
Operation:	k $\rightarrow$ (W); TOS $\rightarrow$ PC
Status Affected:	None
Encoding:	`1000` `kkkk` `kkkk`
Description:	The W register is loaded with the eight-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2

Example:

```
        CALL TABLE;W contains
                  ;table offset
                  ;value.
        •         ;W now has table
        •         ;value.
TABLE   •
        ADDWF PC  ;W = offset
        RETLW k1  ;Begin table
        RETLW k2  ;
        •
        •
        •
        RETLW kn  ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

RLF — Rotate Left f through Carry

Syntax: [*label*] RLF f, d

Operands: $0 \le f \le 31$
$d \in [0,1]$

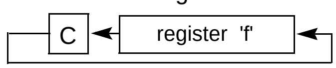
Operation: See description below

Status Affected: C

Encoding:

`0011`	`01df`	`ffff`

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag (STATUS<0>). If 'd' is '`0`', the result is placed in the W register. If 'd' is '`1`', the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example: `RLF REG1,0`

Before Instruction
REG1 = `1110 0110`
C = `0`
After Instruction
REG1 = `1110 0110`
W = `1100 1100`
C = `1`

RRF — Rotate Right f through Carry

Syntax: [*label*] RRF f, d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Encoding:

`0011`	`00df`	`ffff`

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag (STATUS<0>). If 'd' is '`0`', the result is placed in the W register. If 'd' is '`1`', the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example: `RRF REG1,0`

Before Instruction
REG1 = `1110 0110`
C = `0`
After Instruction
REG1 = `1110 0110`
W = `0111 0011`
C = `0`

Sleep — Go into Standby Mode

Syntax: [*label*] Sleep

Operands: None

Operation: 00h → WDT;
0 → WDT prescaler; if assigned
1 → $\overline{TO}$;
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

`0000`	`0000`	`0011`

Description: Time-out Status bit ($\overline{TO}$) is set. The power-down Status bit ($\overline{PD}$) is cleared. The WDT and its prescaler are cleared.
The processor is put into Sleep mode with the oscillator stopped. See section on Sleep for more details.

Words: 1

Cycles: 1

Example: `SLEEP`

SUBWF **Subtract W from f**

Syntax:	[*label*] SUBWF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f) – (W) → (dest)
Status Affected:	C, DC, Z
Encoding:	`0000` `10df` `ffff`
Description:	Subtract (2's complement method) the W register from register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.
Words:	1
Cycles:	1

Example 1: `SUBWF REG1, 1`

Before Instruction
REG1 = 3
W = 2
C = ?
After Instruction
REG1 = 1
W = 2
C = 1 ; result is positive

Example 2:

Before Instruction
REG1 = 2
W = 2
C = ?
After Instruction
REG1 = 0
W = 2
C = 1 ; result is zero

Example 3:

Before Instruction
REG1 = 1
W = 2
C = ?
After Instruction
REG1 = 0xFF
W = 2
C = 0 ; result is negative

SWAPF **Swap Nibbles in f**

Syntax:	[*label*] SWAPF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f<3:0>) → (dest<7:4>); (f<7:4>) → (dest<3:0>)
Status Affected:	None
Encoding:	`0011` `10df` `ffff`
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in W register. If 'd' is '1', the result is placed in register 'f'.
Words:	1
Cycles:	1

Example: `SWAPF REG1, 0`

Before Instruction
REG1 = 0xA5
After Instruction
REG1 = 0xA5
W = 0x5A

TRIS **Load TRIS Register**

Syntax:	[*label*] TRIS f
Operands:	f = 5, 6, 7, 8 or 9
Operation:	(W) → TRIS register f
Status Affected:	None
Encoding:	`0000` `0000` `0fff`
Description:	TRIS register 'f' (f = 5, 6 or 7) is loaded with the contents of the W register.
Words:	1
Cycles:	1

Example: `TRIS PORTB`

Before Instruction
W = 0xA5
After Instruction
TRISB = 0xA5

11.0 ELECTRICAL SPECIFICATIONS FOR PIC16F59 (continued)

Absolute Maximum Ratings(†)

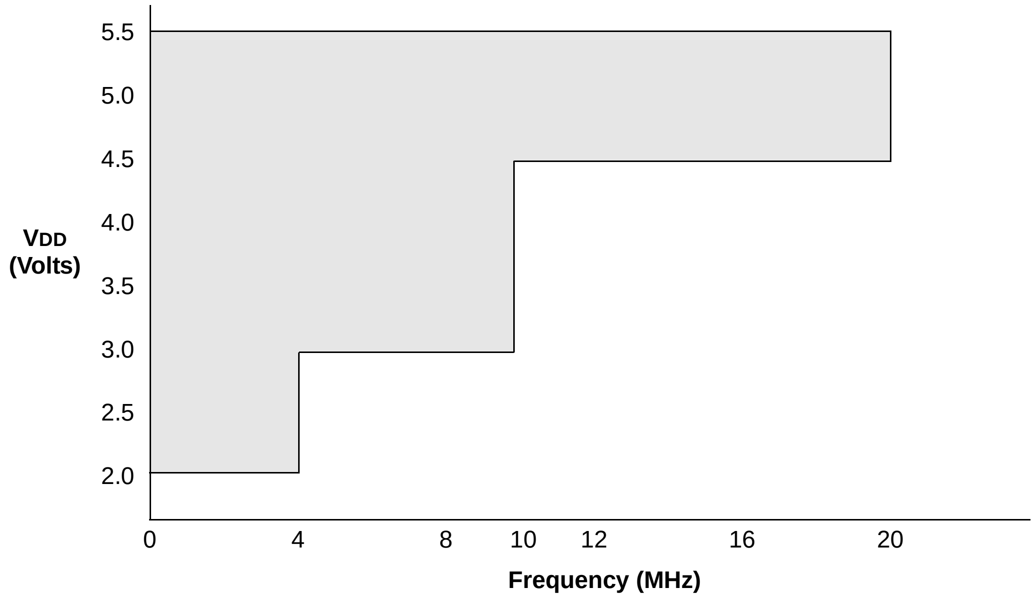
Ambient Temperature under bias .... -40°C to +125°C
Storage Temperature .... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} .... 0V to +6.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS}(1) .... 0V to +13.5V
Voltage on all other pins with respect to V_{SS} .... -0.6V to (V_{DD} + 0.6V)
Total power dissipation(2) .... 900 mW
Max. current out of V_{SS} pins .... 250 mA
Max. current into V_{DD} pins .... 200 mA
Max. current into an input pin (T0CKI only) .... ±500 μA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) .... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) .... ±20 mA
Max. output current sunk by any I/O pin .... 25 mA
Max. output current sourced by any I/O pin .... 25 mA
Max. output current sourced by a single I/O port (PORTA, B, C, D or E) .... 100 mA
Max. output current sunk by a single I/O port (PORTA, B, C, D or E) .... 100 mA

Note 1: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50 to 100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

2: Power Dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

†NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 11-1: PIC16F5X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

11.1 DC Characteristics: PIC16F5X (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Sym.**	**Characteristic/Device**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.0	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage**(1)	—	1.5*	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D010	IDD	**Supply Current**(2)					
			—	170	350	µA	FOSC = 4 MHz, VDD = 2.0V, XT or RC mode(3)
			—	0.4	1.0	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	1.7	5.0	mA	FOSC = 20 MHz, VDD = 5.0V, HS mode
			—	15	22.5	µA	FOSC = 32 kHz, VDD = 2.0V, LP mode, WDT disabled
D020	IPD	**Power-down Current**(2)					
			—	1.0	6.0	µA	VDD = 2.0V, WDT enabled
			—	0.5	2.5	µA	VDD = 2.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature, also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in Sleep mode. The Power-down Current in Sleep mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

11.2 DC Characteristics: PIC16F5X (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ T_A ≤ +125°C for extended				
Param No.	Sym.	Characteristic/Device	Min.	Typ†	Max.	Units	Conditions
D001	V_{DD}	**Supply Voltage**	2.0	—	5.5	V	
D002	V_{DR}	**RAM Data Retention Voltage**(1)	—	1.5*	—	V	Device in Sleep mode
D003	V_{POR}	**VDD Start Voltage** to ensure Power-on Reset	—	V_{SS}	—	V	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D004	S_{VDD}	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D010	I_{DD}	**Supply Current**(2)					
			—	170	450	µA	FOSC = 4 MHz, VDD = 2.0V, XT or RC mode(3)
			—	0.4	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	1.7	7.0	mA	FOSC = 20 MHz, VDD = 5.0V, HS mode
			—	15	40	µA	FOSC = 32 kHz, VDD = 2.0V, LP mode, WDT disabled
D020	I_{PD}	**Power-down Current**(2)					
			—	1.0	15.0	µA	VDD = 2.0V, WDT enabled
			—	0.5	8.0	µA	VDD = 2.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature, also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in Sleep mode. The Power-down Current in Sleep mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

11.4 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T	
F Frequency	T Time

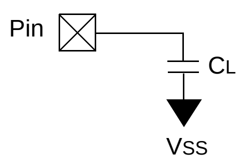
Lowercase letters (pp) and their meanings:

pp	
2 to	mc $\overline{\text{MCLR}}$
ck CLKOUT	osc oscillator
cy cycle time	os OSC1
drt device reset timer	t0 T0CKI
io I/O port	wdt watchdog timer

Uppercase letters and their meanings:

S	
F Fall	P Period
H High	R Rise
I Invalid (High-impedance)	V Valid
L Low	Z High-impedance

FIGURE 11-2: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS – PIC16F5X



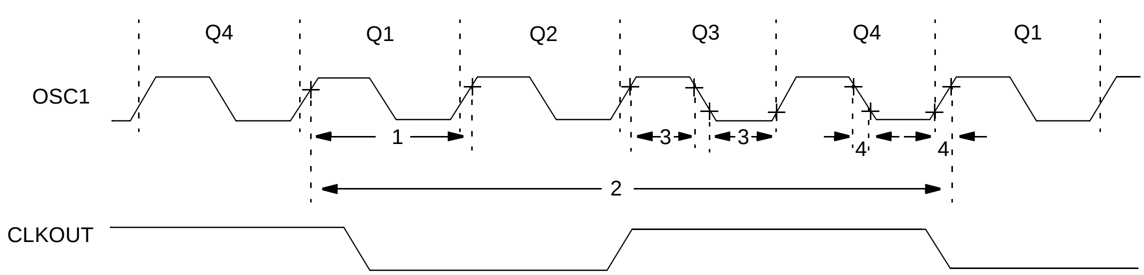
Legend:

C_L = 50 pF for all pins and OSC2 for RC mode

0-15 pF for OSC2 in XT, HS or LP modes when external clock is used to drive OSC1

11.5 Timing Diagrams and Specifications

FIGURE 11-3: EXTERNAL CLOCK TIMING



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